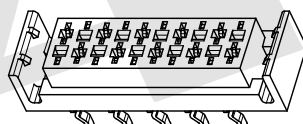
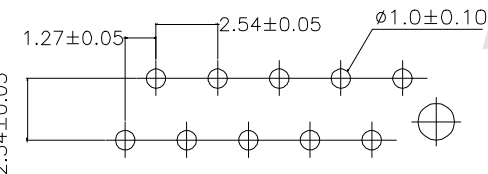


W/O BUMP
Type1



WITH BUMP
Type2



Recommended P.C. Board Layout

PINS	A1	A2	B	C
4	6.98	9.68	3.81	5.58
6	9.52	12.23	6.35	8.12
8	12.06	14.77	8.89	10.66
10	14.60	17.31	11.43	13.20
12	17.14	19.85	13.97	15.74
14	19.68	22.39	16.51	18.28
16	22.22	24.93	19.05	20.82
18	24.76	27.47	21.59	23.36
20	27.30	30.01	24.13	25.90
22	29.84	32.55	26.67	28.44
24	32.38	35.09	29.21	30.98
26	34.92	37.63	31.75	33.52

Unless Otherwise specified tolerance
 X ±0.35 X XX:±0.30
 X I:±0.25 X XXX:±0.15

SCALE: UNIT:
 As Shown mm
 DRAW DATE
 Gong Feng 09/11/2017
 CHECK DATE
 BobYang 09/11/2017

SPECIFICATION

Current Rating: 1.0Amp
Insulation Resistance: 1000MΩ min
Contact Resistance: 20mΩ max
Withstand Voltage: 500V AC/DC
Operating Temperature: -40°C to +105°C
Contact Material: Brass
Contact Plating: Au or Sn Over Ni
Insulator Material: High Temperature plastic
 UL 94V-0

Ordering Code:

MFC501 - X - X - X - X - X
 ① ② ③ ④ ⑤ ⑥

① Series No:

② No. of Contacts
 04P 06P 08P
 10P 12P 14P
 16P 18P 20P
 26P

③ Insulator Material
 A:PBT
 B:PA46
 C:SPECIAL

④ Contact Plating

G0: Gold flash S0: Gold flash/Ni
 G1: 3u" Gold S1: 3u" Gold/Ni
 G2: 5u" Gold S2: 5u" Gold/Ni
 G3: 10u" Gold S3: 10u" Gold/Ni
 G4: 15u" Gold S4: 15u" Gold/Ni
 G5: 30u" Gold S5: 30u" Gold/Ni
 SN: Tin

⑤ Packing

A:Tray B:Bag
 C:Tube D:Tape Reel

⑥ Option

A:Type1 B:Type2



ANTENK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE:
 1.27mm Micro Match Socket 180° DIP

DRAWING NO: MFC501-XXAXX

PRODUCT NO: MFC501-XXAXX

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		



180° ANGULAR POSITION